

APPENDIX

Changes to Claims:

Claims 4 and 10 are canceled.

The following are marked-up versions of amended claims 1, 8, 11, 12 and 14-16:

1. (~~Three Times~~Twice Amended) A method of manufacturing a semiconductor device comprising:

a first step of interposing an adhesive between a surface of a substrate on which an interconnect pattern is formed and a surface of a semiconductor chip on which electrodes are formed, said adhesive having conductive particles dispersed therein; and

a second step in which pressure is applied between said semiconductor chip and said substrate, said interconnect pattern and said electrodes are electrically connected via said conductive particles of said adhesive, and said adhesive is caused to cover substantially all of a lateral surface of said semiconductor chip.

8. (~~Three Times~~Twice Amended) A semiconductor device, comprising:

a semiconductor chip having electrodes; a substrate having an interconnect pattern; and an adhesive, said adhesive having conductive particles dispersed therein;

wherein said electrodes and said interconnect pattern are electrically connected via said conductive particles of said adhesive; and

wherein said adhesive is interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, and said adhesive covers substantially all of a lateral surface of said semiconductor chip.

11. (Twice Amended) The semiconductor device as defined in claim ~~8~~10, wherein said adhesive ~~anisotropic conductive material~~ is provided to cover said interconnect pattern in its entirety.

12. (Amended) The semiconductor device as defined in claim ~~8~~11,

wherein said adhesive includes a shading material.

14. (Twice Amended) A circuit board on which is mounted a semiconductor device, the semiconductor device comprising:

a semiconductor chip having electrodes; a substrate having an interconnect pattern; and an adhesive, said adhesive having conductive particles dispersed therein;

wherein said electrodes and said interconnect pattern are electrically connected via said conductive particles of said adhesive; and

wherein said adhesive is interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, and said adhesive covers substantially all of a lateral surface of said semiconductor chip.

15. (Twice Amended) An electronic instrument having a semiconductor device, the semiconductor device comprising:

a semiconductor chip having electrodes; a substrate having an interconnect pattern; and an adhesive, said adhesive having conductive particles dispersed therein;

wherein said electrodes and said interconnect pattern are electrically connected via said conductive particles of said adhesive; and

wherein said adhesive is interposed between a surface of said substrate on which said interconnect pattern is formed and a surface of said semiconductor chip on which said electrodes are formed, and said adhesive covers substantially all of a lateral surface of said semiconductor chip.

16. (Amended) The semiconductor device as defined in claim 8, wherein at least a part of said adhesive second portion has a thickness substantially the same as said semiconductor chip.